STARPOWER

SEMICONDUCTOR

MOSFET

MD342HFM150C8SN

Molding Type Module

150V/342A 2 in one-package

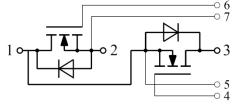
General Description

STARPOWER MOSFET Power Module provides very low $R_{DS(on)}$ as well as optimized intrinsic diode. It's designed for the applications such SMPS and DC drives.



Features

- Low R_{DS(on)}
- Optimized intrinsic reverse diode
- Low inductance case avoid oscillations
- Kelvin source terminals for easy drive
- Isolated copper baseplate using DBC technology



Equivalent Circuit Schematic

Typical Applications

- Main and auxiliary AC drives of electric vehicles
- DC servo and robot drives
- Battery vehicles
- UPS equipment
- Plasma cutting

Absolute Maximum Ratings T_C =25°C unless otherwise noted

Symbol	Description	MD342HFM150C8SN	Units	
$V_{ m DSS}$	Drain-Source Voltage	150	V	
V_{GSS}	Gate-Source Voltage	±30	V	
T	Drain Current @ T _C =25 ℃	342	٨	
I_D	@ T _C =100°C	242	Α	
$I_{\rm F}$	Diode Forward Current	342	A	
P_{D}	Maximum Power Dissipation @ $T_j=175^{\circ}C$	754	W	
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\!\mathbb{C}$	
$T_{ m jop}$	Operating Junction Temperature	-40 to +150	$^{\circ}$ C	
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\mathbb{C}$	
$V_{\rm ISO}$	Isolation Voltage RMS,f=50Hz,t=1min	4000	V	
Mounting	Power Terminal Screw:M5	2.5 to 5.0	N.m	
Torque	Mounting Screw:M6	3.0 to 5.0		
Weight	Weight of Module	200	g	

Electrical Characteristics of MOSFET $T_C=25$ °C unless otherwise noted

Off Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	T _j =25℃	150			V
$I_{ m DSS}$	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0V,$ $T_{j}=25$ °C			40	μΑ
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0V,$ $T_j=25^{\circ}C$			200	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
$V_{GS(th)}$	Gate-Source Threshold Voltage	$I_D=500\mu A, V_{DS}=V_{GS},$ $T_j=25^{\circ}C$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$I_D=206A, V_{GS}=10V,$ $T_j=25$ °C			2.95	mΩ
g_{fs}	Forward Transconductance	V _{DS} =50V,I _D =206A	324			S

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
D	Internal Gate			1.35		Ω
R_{Gint}	Resistance			1.55		52
$t_{d(on)}$	Turn-On Delay Time	V _{DD} =98V,I _D =206A,		27		ns
t_r	Rise Time	$R_{G}=0.5\Omega, V_{GS}=\pm 10 \text{ V},$		119		ns
$t_{d(off)}$	Turn-Off Delay Time	$T_i=25^{\circ}C$		47		ns
t_{f}	Fall Time	1 _j -23 C		84		ns
$egin{array}{c} Q_{\mathrm{g}} \ Q_{\mathrm{gs}} \end{array}$	Total Gate Charge	$I_D=206A, V_{DS}=75V, V_{GS}=10V$		302		nC
Q_{gs}	Gate-Source Charge			104		nC
	Gate-Drain ("Miller")			110		nC
Q_{gd}	Charge					IIC
$\frac{C_{iss}}{C_{oss}}$	Input Capacitance			20.9		nF
C_{oss}	Output Capacitance	$V_{GS}=0V, V_{DS}=50V,$		1.95		nF
C_{rss}	Reverse Transfer	f=1.0MHz		0.41		nF
	Capacitance					
L_{CE}	Stray Inductance				22	nН
R _{CC'+EE'}	Module Lead					
	Resistance, Terminal	$T_{\rm C}$ =25°C		0.65		mΩ
	to Chip					

Electrical Characteristics of Inverse Diode $T_C=25\,^{\circ}C$ unless otherwise

noted

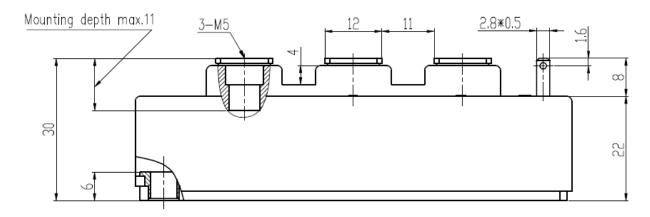
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V_{SD}	Diode Forward Voltage	$I_F=206A, V_{GS}=0V, T_j=25$ °C			1.30	V
t_{rr}	Diode Reverse Recovery Time	V_R =100V, I_F =206A, di/dt=200A/ μ s, T_j =25°C		110		ns
Q _{rr}	Diode Reverse Recovery Charge			1.03		μС

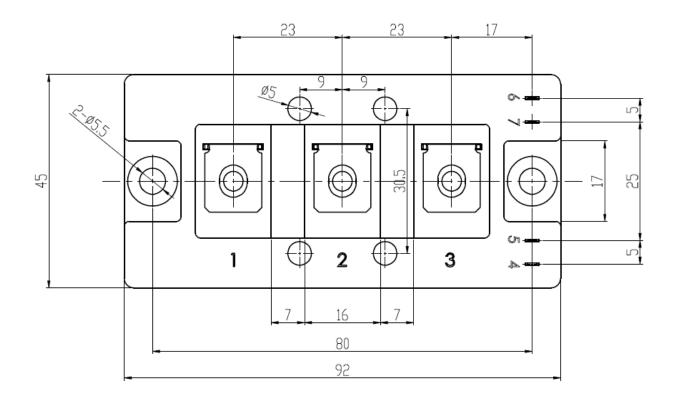
Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{ heta JC}$	Junction-to-Case (per MOSFET)		0.199	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.046		K/W

Package Dimensions

Dimensions in Millimeters





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